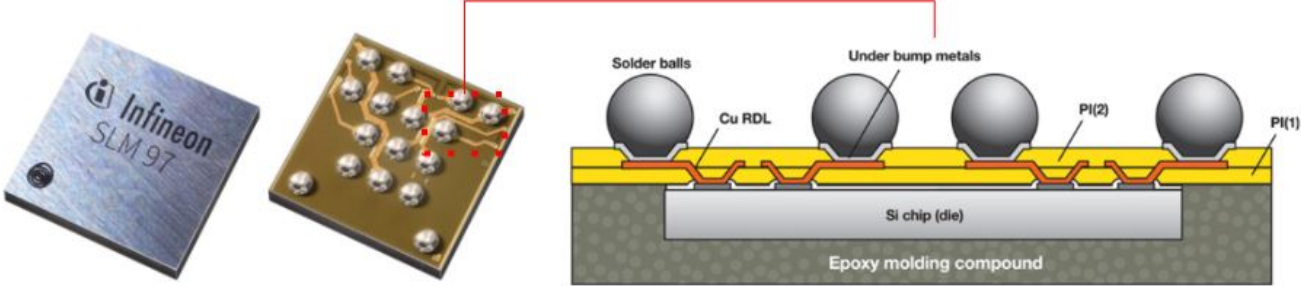


Dielectric Layer Formation

Circuits exposed to the outside of the semiconductor must be protected from external shocks, and the circuits above and below them must be isolated. This is realized by the photolithography process using a photosensitive polyimide.



Wafer Level Package

Cross Sectional View